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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Latchford, et al.

Serial No.: 09/921,938

Confirmation No.: 8367

Filed: August 2, 2001

For: Photolithography Scheme Using a Silicon Containing Resist

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§ Group Art Unit: 1752
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§ Examiner: A. C. Walke
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Box AF
Assistant Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING
37 CFR 1.8
I hereby certify that this correspondence is being deposited on September 6, 2002 with the United States Postal Service as First Class Mail in an envelope addressed to: Box AF Commissioner for Patents, Washington, D.C. 20231.

9/6/02 — Date
Kristi L. Parker — Signature

Dear Sir:

RESPONSE FINAL TO OFFICE ACTION DATED MAY 6, 2002

In response to the Final Office Action dated May 6, 2002, having a shortened statutory period for response extend one-month to expire on September 6, 2002, Applicant requests entry and consideration of the following remarks. Although Applicant believes that no fee is due in conjunction with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/4227.P1/DSM/BCVD/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

In The Claims:

Please amend the claims as follows:

Do Not Enter ACW 9/11/2002

1. (Amended) A method for forming a patterned amorphous carbon layer in a multilayer stack, comprising:

depositing an amorphous carbon layer on a substrate;

depositing a silicon containing photoresist layer on top of the amorphous carbon layer;